



DESCRIPTION

The GLF71325 is an ultra-efficiency, 4A rated, integrated load switch with integrated slew rate control. The best in class efficiency makes it an ideal choice for use in lower power subsystems and mobile electronics.

The GLF71325 features an ultra-efficient I_Q Smart™ technology that supports the lowest R_{ON} , quiescent current (I_Q) and shutdown current (I_{SD}) in the industry. Low R_{ON} reduces conduction losses, while low I_Q and I_{SD} solutions help designers to reduce parasitic leakage current, improve system efficiency, and increase battery lifetime.

The GLF71325 integrated slew rate control greatly enhances system reliability by mitigating bus voltage swings during switching events. Where uncontrolled switches can generate high inrush currents that result in voltage droop and/or bus reset events, the GLF slew rate control specifically limits inrush currents during turn-on to minimize voltage droop.

The GLF71325 can be used in multiple voltage rail applications which helps to simplify inventory management and reduces operating cost.

The GLF71325 offers best in class size and resistance performance utilizing a wafer level chip scale packaging with 6 bumps in a 0.97mm x 1.47mm x 0.55mm die size and a 0.5mm pitch.

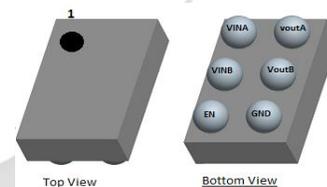
FEATURES

- Wide Input Range: 1.1V to 5.5V
6V abs max
- Controlled Rise Time: 2.2ms at 3.3V_{IN}
- Low R_{ON} : 18m Ω Typ @ 3.3V_{IN}
- Ultra-Low I_Q : 1 nA Typ @ 3.3V_{IN}
- Ultra-Low I_{SD} : 16nA Typ @ 3.3V_{IN}
- I_{OUT} Max: 4A @ 5.5V_{IN}
- Internal EN Pull-Down Resistor
- Integrated Output Discharge Switch
- Wide Operating Temperature Range:
-40°C ~ 105°C
- HBM: 6kV, CDM: 2kV
- Package: 0.97mm x 1.47mm WLCSP

APPLICATIONS

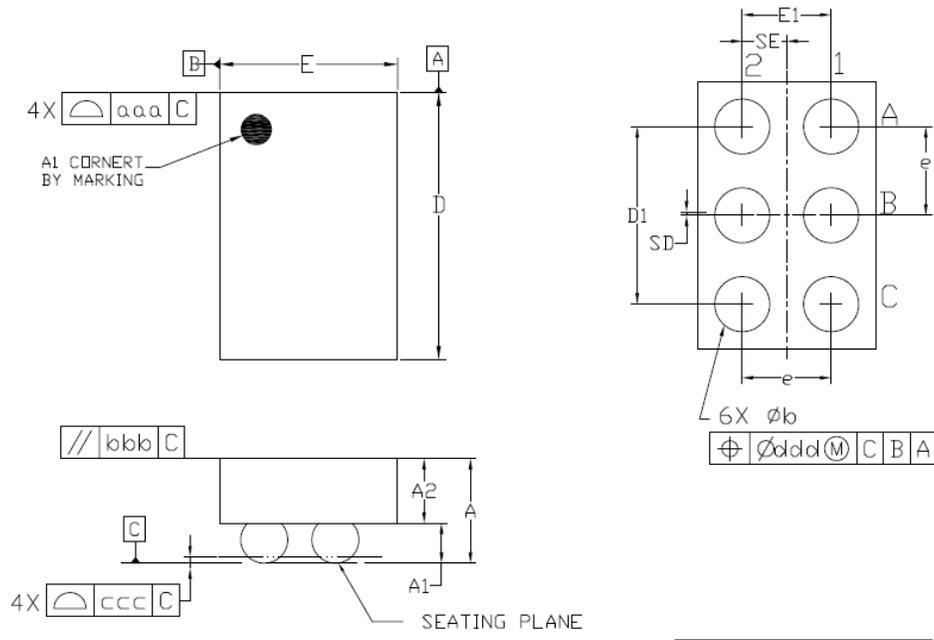
- Low Power Subsystems
- Data Storage, SSD
- Mobile Devices

PACKAGE



0.97mm x 1.47mm x 0.55mm
0.5mm pitch WLCSP

PACKAGE OUTLINE



| Dimensional Ref. | | | |
|-----------------------|-----------|-------|-------|
| REF. | Min. | Nom. | Max. |
| A | 0.500 | 0.550 | 0.600 |
| A1 | 0.225 | 0.250 | 0.275 |
| A2 | 0.275 | 0.300 | 0.325 |
| D | 1.460 | 1.470 | 1.485 |
| E | 0.960 | 0.970 | 0.985 |
| D1 | 0.950 | 1.000 | 1.050 |
| E1 | 0.450 | 0.500 | 0.550 |
| b | 0.260 | 0.310 | 0.360 |
| e | 0.500 BSC | | |
| SD | 0.000 BSC | | |
| SE | 0.250 BSC | | |
| Tol. of Form&Position | | | |
| aaa | 0.10 | | |
| bbb | 0.10 | | |
| ccc | 0.05 | | |
| ddd | 0.05 | | |

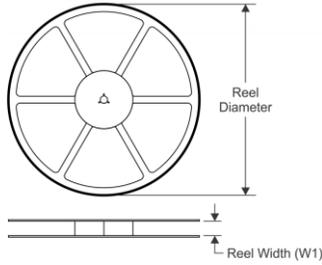
Notes

1. ALL DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.

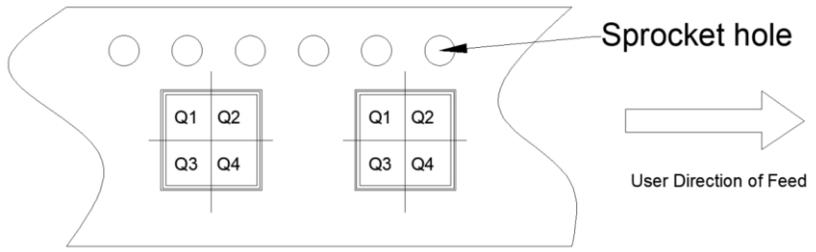
R

TAPE AND REEL INFORMATION

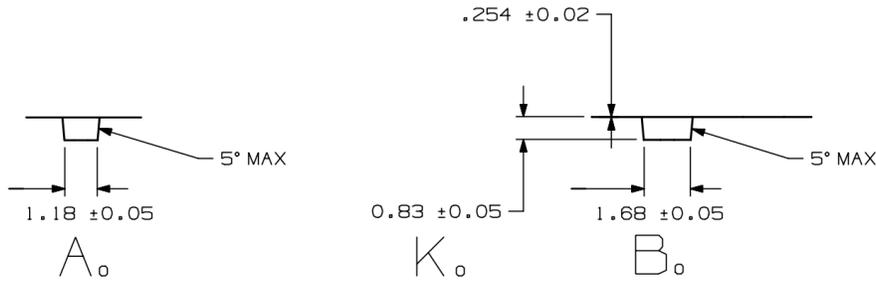
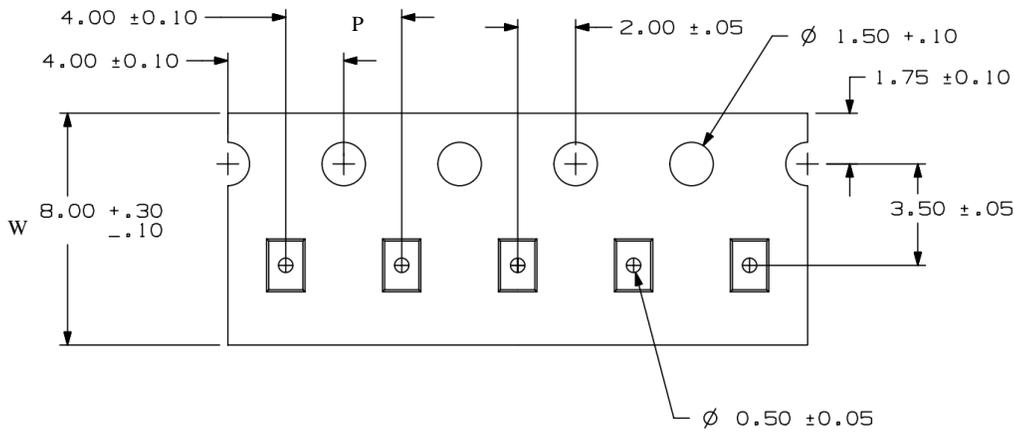
REEL DIMENSIONS



QUADRANT ASSIGNMENTS PIN 1 ORIENTATION TAPE



TAPE DIMENSIONS



| Device | Package | Pins | SPQ | Reel Diameter(mm) | Reel Width W1 | A0 | B0 | K0 | P | W | Pin1 |
|----------|---------|------|------|-------------------|---------------|------|------|------|---|---|------|
| GLF72125 | WLCSP | 6 | 3000 | 180 | 9 | 1.18 | 1.68 | 0.83 | 4 | 8 | Q1 |

Remark:

- A0: Dimension designed to accommodate the component width
- B0: Dimension designed to accommodate the component length
- C0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P: Pitch between successive cavity centers